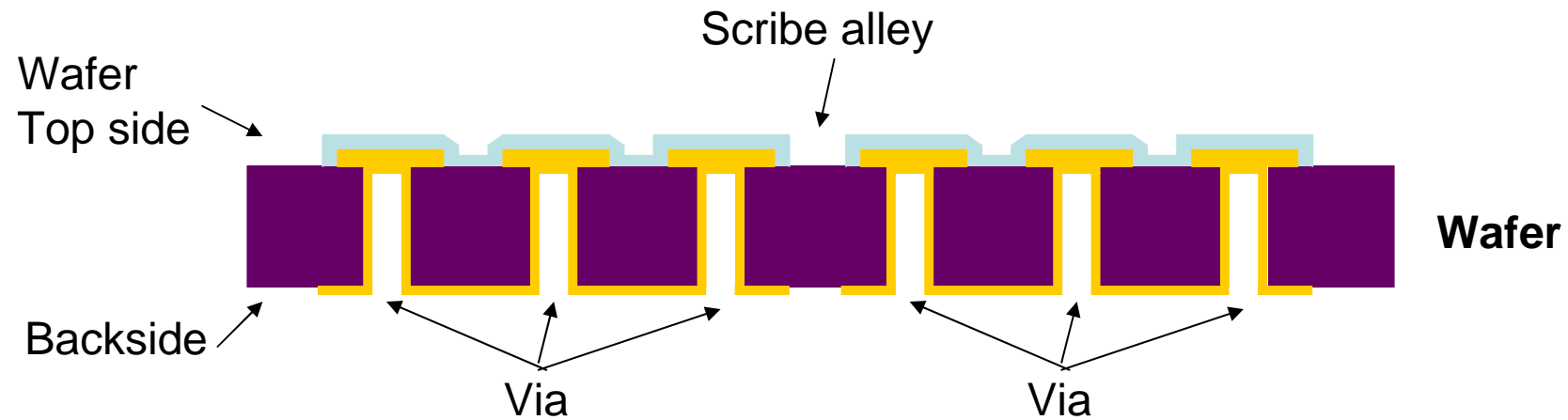


Wafer with Backside Via



Backside via process is the process to make the via to connect all the ground/source in an IC together. The via metal is made of plated Au.